



Material Content Data Sheet



Sales Product Name		TDA5211		Issued		7. September 2015		
MA#		MA000223761						
Package		PG-TSSOP-28-1		Weight*		107.00 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.457	2.30	2.30	22966	22966
leadframe	non noble metal	nickel	7440-02-0	14.398	13.46		134561	
	non noble metal	iron	7439-89-6	19.882	18.58	32.04	185822	320383
wire	noble metal	gold	7440-57-5	0.938	0.88	0.88	8768	8768
encapsulation	organic material	carbon black	1333-86-4	0.196	0.18		1833	
	plastics	epoxy resin	-	8.301	7.76		77585	
	inorganic material	silicondioxide	60676-86-0	56.867	53.15	61.09	531486	610904
leadfinish	non noble metal	tin	7440-31-5	1.559	1.46	1.46	14568	14568
plating	noble metal	silver	7440-22-4	1.416	1.32	1.32	13231	13231
glue	plastics	acrylic resin	-	0.196	0.18		1836	
	noble metal	silver	7440-22-4	0.786	0.73	0.91	7344	9180
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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